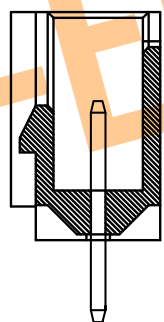
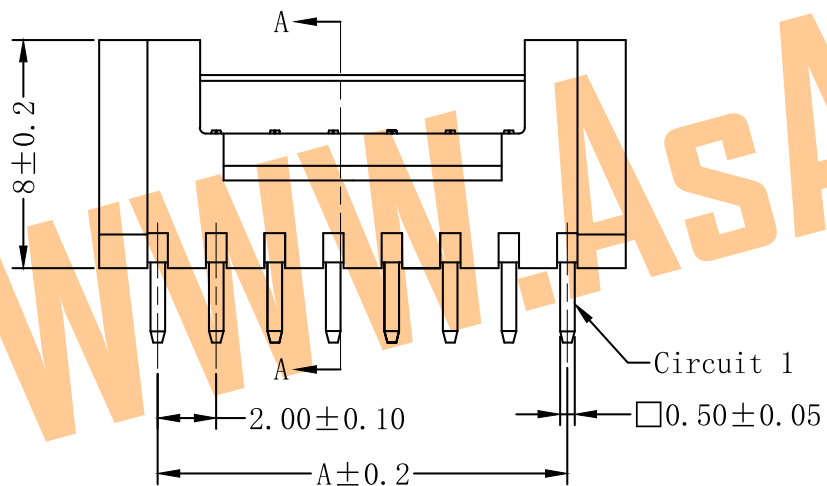


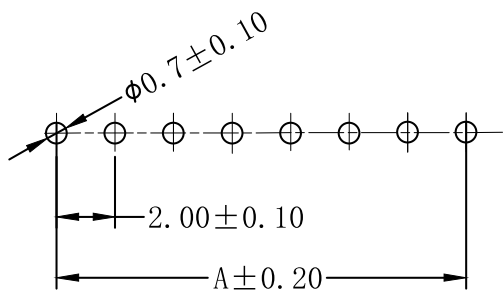
技术要求:

- 1、塑件材料: CM3004 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻:  $\leq 10m\Omega$
- 4、绝缘电阻:  $\geq 1000M\Omega$
- 5、额定电压: 250V AC DC
- 6、额定电流: 2.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度:  $-25 \sim +85$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $220^{+5}_{-0}$ , 时间  $2.5 \pm 0.5$ 秒
- 10、铅和镉等六大有害物质含量要符合环保要求



SECTION A-A

Circuits	Dimensions (mm)		
	A	B	C
02	2.00	6.10	2.50
03	4.00	8.00	2.50
04	6.00	10.00	3.50
05	8.00	12.00	5.50
06	10.00	14.00	7.50
07	12.00	16.00	9.50
08	14.00	18.00	11.50
09	16.00	20.00	13.50
10	18.00	22.00	15.50
11	20.00	24.00	15.50
12	22.00	26.00	15.50
13	24.00	28.00	15.50
14	26.00	30.00	15.50
15	28.00	32.00	15.50

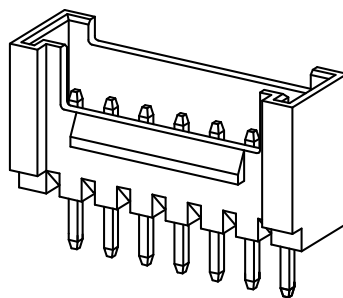


SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)



AsA Electronic Co.

Tel : (+98) 21 66 73 56 82 Mob : (+98) 912 03 161 02



序号	名称	材料	数量	附注
2	端子 Contact	黄铜	n x 1	电镀层: 整个表面镀层 30u"MIN, 厚度 80u"MIN.
1	基板 Wafer	LCP (UL94V-0)	1	白色

GENERAL TOLERANCES				DRAWN BY 绘图者	
0.X	$\pm 0.25$	X°	$\pm 3^\circ$	CHK. BY	审核者
0.XX	$\pm 0.12$			APRV. BY	批准人
0.XXX	$\pm 0.05$	X.X°	$\pm 0.5^\circ$	DRAWING NO.	
UNIT	SIZE	SCALE		SHEET	PROD. NAME
MM	A4	1:1		10F1	PART NO.
				TITLE	

HY2.0

BX-HY2.0-